

### **AMENDMENT TO THE DRAWINGS**

Figs. 1 and 2 have been amended. The attached sheet of formal drawings replaces the original sheet including Figs. 1-6.

### **REMARKS/ARGUMENTS**

The applicants' attorneys appreciate the Examiner's thorough search and remarks.

Responsive to the objections against Figs. 1 and 2, Figs. 1 and 2 have been corrected as suggested by the Examiner. Withdrawal of the objections is requested.

Claims 26-41 are new. Claims 26-34 depend from claim 1, and claims 35-41 depend from claim 7. Entry of claims 26-41 is requested.

Claim 1 has been amended and now calls for a mold compound that covers the outer surfaces of the web and the leg of the electrical connector. Furthermore, claim 1 has been amended to call for the leg to include a free surface which faces the same direction as the second power contact of the device.

Kajiwara et al. (Kajiwara), U.S. Patent No. 6,774,466, which was cited as anticipating the previous version of claim 1, shows conductor 54/58 in which the leg portion is outside of molded body 59. Stated another way, mold compound 59 does not cover the outside surface of the leg portion of conductor 54/58. Consequently, the bend in conductor 54/58 is disposed outside of mold compound 59. As a result, any force applied to the end portion of conductor 54/58 (for example, during assembly) causes a bending moment, which is transferred to molded body 59, and may cause defects such as fractures, etc.

In addition, the free surface of electrical connector 54/58 is disposed outside of molded body 59, and as seen, for example in Fig. 4(a) even extends laterally away from molded body 59. As a result, the footprint of the package shown by Kajiwara is larger than molded body 59, i.e. the housing for the die.

On the other hand, in a package according to claim 1, the mold compound covers the exterior surface of the web portion and resides also on the outer surface of the leg. Thus, the bend in the conductor is disposed within the mold compound, whereby creation of bending moments and consequent damage to the mold compound due to such external factors is minimized.

In addition, the claim calls for the free surface of the conductor to face the same direction as the second power contact of the device. This feature, in combination with other features, allows for having the free surface within the boundaries of the molded housing. Thus, a package

according to claim 1 would have a smaller footprint, which is desirable. Claim 1 is, therefore, distinguishable over Kajiwara. Reconsideration is requested.

Claim 7 has been amended to call for a "cup-shaped clip". In the Office Action it has been recognized that a cup-shaped clip is not shown in the prior art. Thus, claim 7 should be deemed allowable over the art of record.

Claims 13 and 25 have been amended to improve the form thereof. These claims have been deemed allowable for including a cup-shaped clip. That limitation is still called for in claims 13 and 25. Confirmation of allowability of claims 13 and 25 is requested.

The remaining claims are dependent claims. Each of these claims includes additional limitations, which in combination with those of its base claim, are not shown or suggested by the art of record. Reconsideration is requested.

The application is believed to be in condition for allowance. Such action is earnestly solicited.

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Kourosh Salehi

Name of applicant, assignee or  
Registered Representative

Signature

June 24, 2005

Date of Signature

Respectfully submitted,

Kourosh Salehi

Registration No.: 43,898

OSTROLENK, FABER, GERB & SOFFEN, LLP

1180 Avenue of the Americas

New York, New York 10036-8403

Telephone: (212) 382-0700

KS:gl